



All dimensions are in mm

Interface

According to RN 108-04

Documents

PCB layout MB_639
T&R packaging tbd

Material and plating

Connector parts

- Center contact
- Interface
- PCB
- Outer contact (Interface)
- Outer contact (PCB)
- Dielectric
- Housing

Material
Bronze

Bronze
Zinc alloy
LCP
HTN

Plating

Gold, min. 0.15 µm, over nickel
Tin, min. 0.5 µm, over nickel
Tin, min. 1.5 µm
Tin, min. 2 µm

Preliminary

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Electrical data

Impedance	50 Ω
Frequency	DC to 9 GHz
Return loss	≥ 25 dB, DC ≤ 3 GHz ≥ 20 dB, > 3 GHz ≤ 6 GHz ≥ 12 dB, > 6 GHz ≤ 9 GHz
Insertion loss	≤ 0.1 x √f(GHz) dB
Insulation resistance	≥ 1x10 ³ MΩ
Center contact resistance	≤ 10 mΩ
Outer contact resistance	≤ 5 mΩ
Test voltage	≤ 800 V rms
Working voltage	≤ 60 V rms
Power current	≤ 1 A DC
Cross talk (optional)	≤ -60 dB up to 10 GHz

– Connector only, VSWR in application depends decisive on PCB layout –

Mechanical data

Mating cycles	≥ 25
Engagement force	≤ 45 N*
Disengagement force	≥ 5 N
Retention force latch	≥ 110 N
Coding efficiency	≥ 150 N

* according to USCAR 25 Rev. 3, tests specified in USCAR 17 Rev. 5 TG-G

Environmental data

Temperature range	-40 °C to +105 °C
Thermal shock	ISO 20860-2 clause 9.2
Temperature and humidity	ISO 20860-2 clause 9.3
Vibration and mechanical shock	ISO 20860-2 clause 9.1
Dry heat	ISO 20860-2 clause 9.4
Soldering profile	acc. to IEC 60068-2-58; Group 3 (250 °C / 30 s)
RoHS	compliant

Packing

Standard	tbd pcs in tape & reel
Weight	3.8 g

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